



TISP4C125H3BJ THRU TISP4C395H3BJ

LOW CAPACITANCE BIDIRECTIONAL THYRISTOR OVERVOLTAGE PROTECTORS

TISP4CxxxH3BJ Overvoltage Protector Series

Ion-Implanted Breakdown Region

- Precise and Stable Voltage
- Low Voltage Overshoot under Surge
- Low Off-State Capacitance

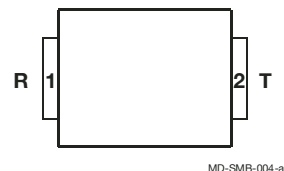
Device Name	V_{DRM} V	$V_{(BO)}$ V
TISP4C125H3BJ	100	125
TISP4C145H3BJ	120	145
TISP4C180H3BJ	145	180
TISP4C220H3BJ	180	220
TISP4C250H3BJ	190	250
TISP4C290H3BJ	220	290
TISP4C350H3BJ	275	350
TISP4C395H3BJ	320	395

Rated for International Surge Wave Shapes

Wave Shape	Standard	I_{PPSM} A
2/10	GR-1089-CORE	500
10/160	TIA-968-A	200
10/700	ITU-T K.20/21/45	150
10/560	TIA-968-A	100
10/1000	GR-1089-CORE	100

UL TISP4C290H3BJ, TISP4C350H3BJ & TISP4C395H3BJ
are UL Recognized Components

SMB Package (Top View)



Device Symbol



Description

This device is designed to limit overvoltages on the telephone line. Overvoltages are normally caused by a.c. power system or lightning flash disturbances which are induced or conducted on to the telephone line. A single device provides 2-point protection and is typically used for the protection of 2-wire telecommunication equipment (e.g. between the Ring and Tip wires for telephones and modems). Combinations of devices can be used for multi-point protection (e.g. 3-point protection between Ring, Tip and Ground).

The protector consists of a symmetrical voltage-triggered bidirectional thyristor. Overvoltages are initially clipped by breakdown clamping until the voltage rises to the breakover level, which causes the device to crowbar into a low-voltage on state. This low-voltage on state causes the current resulting from the overvoltage to be safely diverted through the device. The high crowbar holding current prevents d.c. latchup as the diverted current subsides.

Please contact your Bourns representative if the protection voltage you require is not listed.

How to Order

Device	Package	Carrier	For Standard Termination Finish Order As	For Lead Free Termination Finish Order As	Marking Code	Std. Qty.
TISP4CxxxH3BJ	SMB	Embossed Tape Reeled	TISP4CxxxH3BJR	TISP4CxxxH3BJR-S	4CxxxH	3000

Insert xxx corresponding to device name.

*RoHS Directive 2002/95/EC Jan 27 2003 including Annex

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Specifications are subject to change without notice.

Customers should verify actual device performance in their specific applications.

TISP4CxxxH3BJ Overvoltage Protector Series

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Absolute Maximum Ratings, $T_A = 25\text{ }^{\circ}\text{C}$ (Unless Otherwise Noted)

Rating	Symbol	Value	Unit
Repetitive peak off-state voltage	V_{DRM}	'4C125H3BJ ± 100 '4C145H3BJ ± 120 '4C180H3BJ ± 145 '4C220H3BJ ± 180 '4C250H3BJ ± 190 '4C290H3BJ ± 220 '4C350H3BJ ± 275 '4C395H3BJ ± 320	V
Non-repetitive peak impulse current (see Notes 1 and 2) 2/10 μs (GR-1089-CORE, 2/10 μs voltage wave shape) 10/160 μs (TIA-968-A, 10/160 μs voltage wave shape) 5/310 μs (ITU-T K.44, 10/700 μs voltage wave shape used in K.20/21/45) 10/560 μs (TIA-968-A, 10/560 μs voltage wave shape) 10/1000 μs (GR-1089-CORE, 10/1000 μs voltage wave shape)	I_{PPSM}	± 500 ± 200 ± 150 ± 100 ± 100	A
Non-repetitive peak on-state current (see Notes 1, 2 and 3) 20 ms, 50 Hz (full sine wave) 1000 s, 50 Hz	I_{TSM}	30 2.1	A
Junction temperature	T_J	-40 to +150	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	-65 to +150	$^{\circ}\text{C}$

- NOTES: 1. Initially the device must be in thermal equilibrium with $T_J = 25\text{ }^{\circ}\text{C}$.
 2. The surge may be repeated after the device returns to its initial conditions.
 3. EIA/JESD51-2 environment and EIA/JESD51-3 PCB with standard footprint dimensions connected with 5 A rated printed wiring track widths.

Electrical Characteristics, $T_A = 25\text{ }^{\circ}\text{C}$ (Unless Otherwise Noted)

Parameter	Test Conditions	Min	Typ	Max	Unit
I_{DRM} Repetitive peak off-state current	$V_D = V_{\text{DRM}}$ $T_A = 25\text{ }^{\circ}\text{C}$ $T_A = 85\text{ }^{\circ}\text{C}$			± 5 ± 10	μA
$V_{(\text{BO})}$ Breakover voltage	$dv/dt = \pm 250\text{ V/ms}$, $R_{\text{SOURCE}} = 300\text{ }\Omega$			'4C125H3BJ ± 125 '4C145H3BJ ± 145 '4C180H3BJ ± 180 '4C220H3BJ ± 220 '4C250H3BJ ± 250 '4C290H3BJ ± 290 '4C350H3BJ ± 350 '4C395H3BJ ± 395	V
$V_{(\text{BO})}$ Impulse breakover voltage	$dv/dt \leq \pm 1000\text{ V}/\mu\text{s}$, Linear voltage ramp, Maximum ramp value = $\pm 500\text{ V}$ $di/dt = \pm 10\text{ A}/\mu\text{s}$, Linear current ramp, Maximum ramp value = $\pm 10\text{ A}$			'4C125H3BJ ± 135 '4C145H3BJ ± 155 '4C180H3BJ ± 190 '4C220H3BJ ± 230 '4C250H3BJ ± 260 '4C290H3BJ ± 300 '4C350H3BJ ± 360 '4C395H3BJ ± 405	V
$I_{(\text{BO})}$ Breakover current	$dv/dt = \pm 250\text{ V/ms}$, $R_{\text{SOURCE}} = 300\text{ }\Omega$			± 600	mA
V_T On-state voltage	$I_T = \pm 5\text{ A}$, $t_w = 100\text{ }\mu\text{s}$			± 3	V
I_H Holding current	$I_T = \pm 5\text{ A}$, $di/dt = \pm 30\text{ mA/ms}$	± 150		± 600	mA
C_O Off-state capacitance	$f = 1\text{ MHz}$, $V_d = 1\text{ V rms}$, $V_D = -2\text{ V}$	'4C125H3BJ		50	pF
		'4C145H3BJ			
		'4C180H3BJ		45	
		'4C220H3BJ			
		'4C250H3BJ			
		'4C290H3BJ		40	
		'4C350H3BJ			
		'4C395H3BJ			

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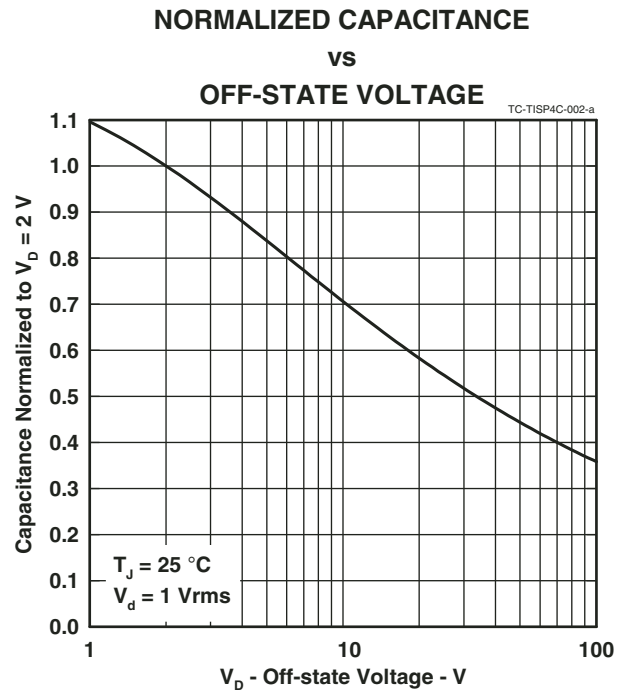
Parameter		Test Conditions	Min	Typ	Max	Unit
R _{θJA}	Junction to ambient thermal resistance	EIA/JESD51-3 PCB, I _T = I _{TSM(1000)} (see Note 4)			113	°C/W
		265 mm x 210 mm populated line card, 4-layer PCB, I _T = I _{TSM(1000)}		50		

Parameter Measurement Information



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Typical Characteristics



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